

SN74AUP1G57 Low-Power Configurable Multiple-Function Gate

1 Features

- Available in the Texas Instruments NanoStar™ Packages
- Low Static-Power Consumption ($I_{CC} = 0.9 \mu\text{A}$ Maximum)
- Low Dynamic-Power Consumption ($C_{pd} = 4.3 \text{ pF}$ Typical at 3.3 V)
- Low Input Capacitance ($C_i = 1.5 \text{ pF}$ Typical)
- Low Noise – Overshoot and Undershoot $<10\%$ of V_{CC}
- I_{off} Supports Partial-Power-Down Mode Operation
- Includes Schmitt-Trigger Inputs
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 5.3 \text{ ns}$ Maximum at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)

2 Applications

- Active Noise Cancellation (ANC)
- Barcode Scanners
- Blood Pressure Monitors
- CPAP Machines
- Cable Solutions
- E-Books
- Embedded PCs
- Field Transmitter: Temperature or Pressure Sensors
- HVAC: Heating, Ventilating, and Air Conditioning
- Network-Attached Storage (NAS)
- Server Motherboard and PSU
- Software Defined Radio (SDR)
- TV: High-Definition (HDTV), LCD, and Digital
- Video Communications Systems

3 Description

The SN74AUP1G57 device features configurable multiple functions. The output state is determined by eight patterns of 3-bit input. The user can choose the logic functions AND, OR, NAND, NOR, XNOR, inverter, and noninverter. All inputs can be connected to V_{CC} or GND.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74AUP1G57YFP	DSBGA (6)	1.16 x 0.76 mm
SN74AUP1G57YZP	DSBGA (6)	1.388 x 0.888 mm
SN74AUP1G57DRY	SON (6)	1.00 x 1.45 mm
SN74AUP1G57DSF	SON (6)	1.00 x 1.00 mm
SN74AUP1G57DBV	SOT-23 (6)	2.80 x 2.90 mm
SN74AUP1G57DCK	SC70 (6)	2.10 x 2.00 mm
SN74AUP1G57DRL	SOT (6)	1.60 x 1.60 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Functional Block Diagram (Positive Logic)

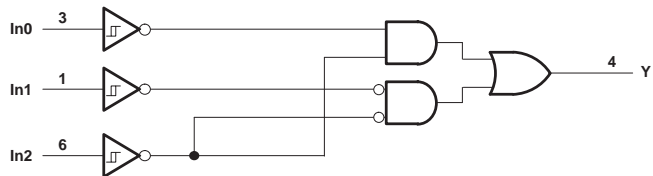


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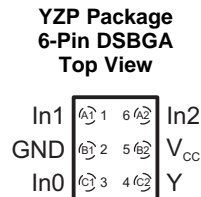
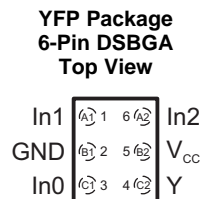
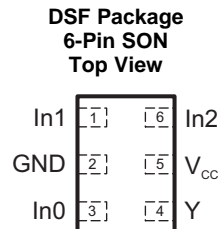
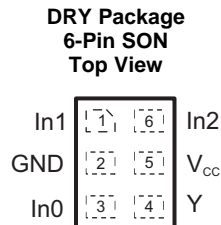
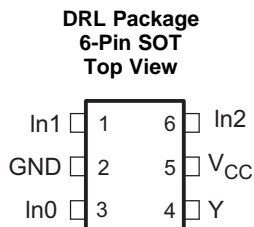
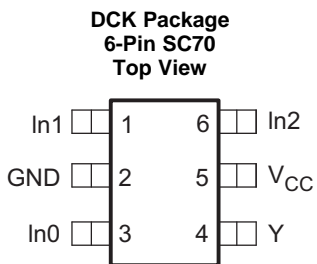
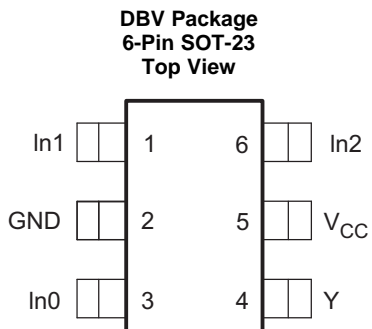
4 Revision History

Changes from Revision I (May 2010) to Revision J

Page

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section **1**

5 Pin Configuration and Functions



Pin Functions

NAME	PIN		I/O	DESCRIPTION
	SOT-23, SC70, SOT	DSBGA		
In1	1	A1	I	Logic input 1
GND	2	B1	—	Ground
In0	3	C1	I	Logic input 0
Y	4	C2	O	Logic output
V _{CC}	5	B2	—	Power
In2	6	A2	I	Logic input 2

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	-0.5	4.6	V
V _I	Input voltage ⁽²⁾	-0.5	4.6	V
V _O	Voltage applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	4.6	V
V _O	Output voltage in the high or low state ⁽²⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0	-50	mA
I _{OK}	Output clamp current	V _O < 0	-50	mA
I _O	Continuous output current		±20	mA
	Continuous current through V _{CC} or GND		±50	mA
T _J	Junction temperature		150	°C
T _{stg}	Storage temperature	-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	1000

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	0.8	3.6	V
V _I	Input voltage	0	3.6	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 0.8 V	-20	μA
		V _{CC} = 1.1 V	-1.1	mA
		V _{CC} = 1.4 V	-1.7	
		V _{CC} = 1.65 V	-1.9	
		V _{CC} = 2.3 V	-3.1	
		V _{CC} = 3 V	-4	
I _{OL}	Low-level output current	V _{CC} = 0.8 V	20	μA
		V _{CC} = 1.1 V	1.1	mA
		V _{CC} = 1.4 V	1.7	
		V _{CC} = 1.65 V	1.9	
		V _{CC} = 2.3 V	3.1	
		V _{CC} = 3 V	4	
T _A	Operating free-air temperature	-40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾	SN74AUP1G57						UNIT
	DBV (SOT-23)	DCK (SC70)	DRL (SOT)	DSF (SON)	DRY (SON)	YFP/YZP (DSBGA)	
	6 PINS	6 PINS	6 PINS	6 PINS	6 PINS	6 PINS	
R _{θJA} Junction-to-ambient thermal resistance	165	259	142	300	234	123	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{T+} Positive-going input threshold voltage		0.8 V	0.3		0.6	0.3	0.6	V
		1.1 V	0.53		0.9	0.53	0.9	
		1.4 V	0.74		1.11	0.74	1.11	
		1.65 V	0.91		1.29	0.91	1.29	
		2.3 V	1.37		1.77	1.37	1.77	
		3 V	1.88		2.29	1.88	2.29	
V _{T-} Negative-going input threshold voltage		0.8 V	0.1		0.6	0.1	0.6	V
		1.1 V	0.26		0.65	0.26	0.65	
		1.4 V	0.39		0.75	0.39	0.75	
		1.65 V	0.47		0.84	0.47	0.84	
		2.3 V	0.69		1.04	0.69	1.04	
		3 V	0.88		1.24	0.88	1.24	
ΔV _T Hysteresis (V _{T+} – V _{T-})		0.8 V	0.07		0.5	0.07	0.5	V
		1.1 V	0.08		0.46	0.08	0.46	
		1.4 V	0.18		0.56	0.18	0.56	
		1.65 V	0.27		0.66	0.27	0.66	
		2.3 V	0.53		0.92	0.53	0.92	
		3 V	0.79		1.31	0.79	1.31	
V _{OH}	I _{OH} = –20 μA	0.8 V to 3.6 V	V _{CC} – 0.1		V _{CC} – 0.1		V	
	I _{OH} = –1.1 mA	1.1 V	0.75 × V _{CC}		0.7 × V _{CC}			
	I _{OH} = –1.7 mA	1.4 V	1.11		1.03			
	I _{OH} = –1.9 mA	1.65 V	1.32		1.3			
	I _{OH} = –2.3 mA	2.3 V	2.05		1.97			
	I _{OH} = –3.1 mA		1.9		1.85			
	I _{OH} = –2.7 mA	3 V	2.72		2.67			
	I _{OH} = –4 mA		2.6		2.55			
V _{OL}	I _{OL} = 20 μA	0.8 V to 3.6 V			0.1		V	
	I _{OL} = 1.1 mA	1.1 V			0.3 × V _{CC}			
	I _{OL} = 1.7 mA	1.4 V			0.31			
	I _{OL} = 1.9 mA	1.65 V			0.31			
	I _{OL} = 2.3 mA	2.3 V			0.31			
	I _{OL} = 3.1 mA				0.44			
	I _{OL} = 2.7 mA	3 V			0.31			
	I _{OL} = 4 mA				0.44			
I _I (all inputs)	V _I = GND to 3.6 V	0 V to 3.6 V			0.1		μA	
I _{off}	V _I or V _O = 0 V to 3.6 V	0 V			0.2		μA	

Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
ΔI _{off}	V _I or V _O = 0 V to 3.6 V	0 V to 0.2 V			0.2		0.6	μA
I _{CC}	V _I = GND or (V _{CC} to 3.6 V), I _O = 0	0.8 V to 3.6 V			0.5		0.9	μA
ΔI _{CC}	V _I = V _{CC} – 0.6 V ⁽¹⁾ , I _O = 0	3.3 V			40		50	μA
C _i	V _I = V _{CC} or GND	0 V		1.5				pF
		3.6 V		1.5				
C _o	V _O = GND	0 V		3				pF

 (1) One input at V_{CC} – 0.6 V, other inputs at V_{CC} or GND.

6.6 Switching Characteristics, C_L = 5 pF

 over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see [Figure 2](#) and [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	In0, In1, or In2	Y	0.8 V		28.6				ns
			1.2 V ± 0.1 V	2.6	9.5	13.6	2.1	17.1	
			1.5 V ± 0.1 V	1.9	6.4	9.1	1.4	11.1	
			1.8 V ± 0.15 V	1.4	5.2	7.1	0.9	8.9	
			2.5 V ± 0.2 V	1.1	3.6	5.3	0.6	6.3	
			3.3 V ± 0.3 V	1	2.9	4.4	0.5	5.3	

6.7 Switching Characteristics, C_L = 10 pF

 over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see [Figure 2](#) and [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	In0, In1, or In2	Y	0.8 V		32.8				ns
			1.2 V ± 0.1 V	2.6	11	15.1	2.1	18.1	
			1.5 V ± 0.1 V	1.9	7.4	10.3	1.4	12.4	
			1.8 V ± 0.15 V	1.4	6	8.1	0.9	10	
			2.5 V ± 0.2 V	1.1	4.3	6.1	0.6	7.3	
			3.3 V ± 0.3 V	1	3.5	5.1	0.5	6.1	

6.8 Switching Characteristics, C_L = 15 pF

 over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see [Figure 2](#) and [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	In0, In1, or In2	Y	0.8 V		37				ns
			1.2 V ± 0.1 V	3.6	12.3	16.8	3.1	20.1	
			1.5 V ± 0.1 V	2.8	8.3	11.4	2.3	13.7	
			1.8 V ± 0.15 V	2.1	6.7	9	1.6	11.1	
			2.5 V ± 0.2 V	1.7	4.9	6.8	1.2	8.1	
			3.3 V ± 0.3 V	1.5	3.9	5.6	1	6.7	

6.9 Switching Characteristics, C_L = 30 pF

over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see [Figure 2](#) and [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	In0, In1, or In2	Y	0.8 V	49.3					ns
			1.2 V ± 0.1 V	5	15.7	21.4	4.5	26.5	
			1.5 V ± 0.1 V	3.9	10.8	14.4	3.4	17.4	
			1.8 V ± 0.15 V	3.1	8.8	11.4	2.6	14	
			2.5 V ± 0.2 V	2.6	6.4	8.4	2.1	10.1	
			3.3 V ± 0.3 V	2.3	5.3	7	1.8	8.4	

6.10 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V _{CC}	TYP	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	0.8 V	4	pF
			1.2 V ± 0.1 V	4	
			1.5 V ± 0.1 V	4	
			1.8 V ± 0.15 V	4	
			2.5 V ± 0.2 V	4.1	
			3.3 V ± 0.3 V	4.3	

6.11 Typical Characteristics

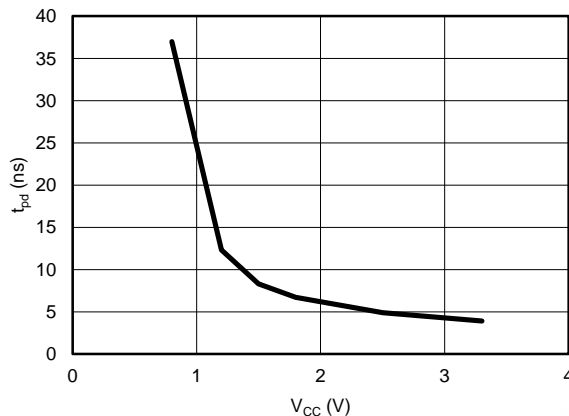
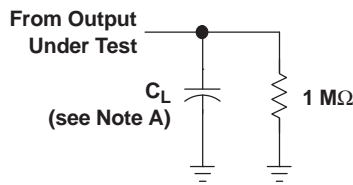


Figure 1. t_{pd} vs V_{CC}, 15-pF Load

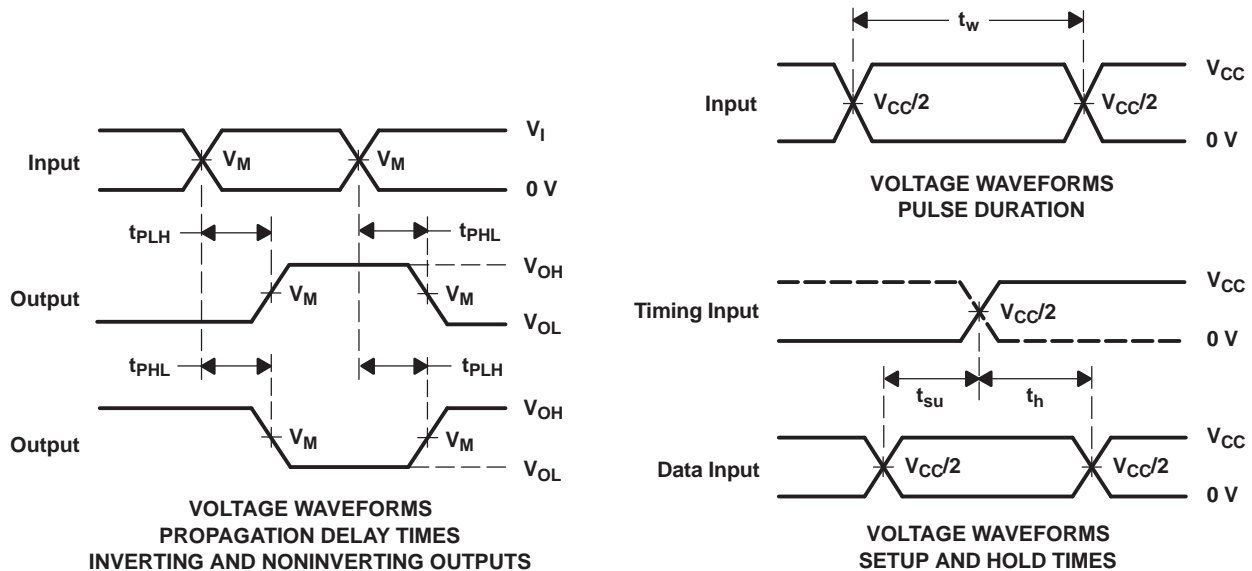
7 Parameter Measurement Information

7.1 Propagation Delays, Setup and Hold Times, and Pulse Duration



LOAD CIRCUIT

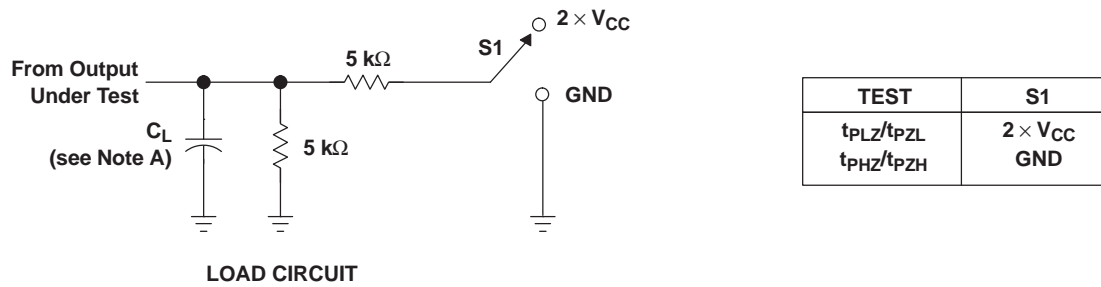
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



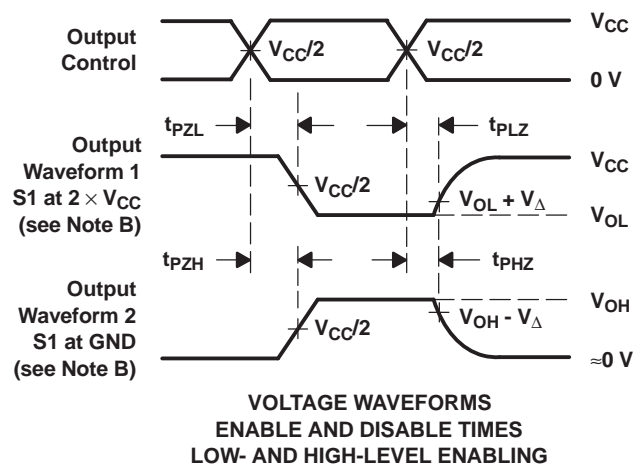
- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$, slew rate ≥ 1 V/ns.
 C. The outputs are measured one at a time, with one transition per measurement.
 D. t_{PLH} and t_{PHL} are the same as t_{pd} .
 E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

7.2 Enable and Disable Times



	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_{Δ}	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$, slew rate ≥ 1 V/ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The AUP family is TI's premier solution to the low-power needs of the industry in battery-powered portable applications. This family ensures a very low static and dynamic power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity, which produces very low undershoot and overshoot characteristics.

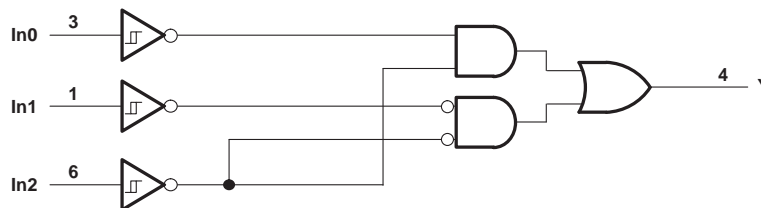
The SN74AUP1G57 features configurable multiple functions. The output state is determined by eight patterns of 3-bit input. The user can choose the logic functions AND, OR, NAND, NOR, XNOR, inverter, and noninverter. All inputs can be connected to V_{CC} or GND.

The device functions as an independent gate with Schmitt-trigger inputs, which allow for slow input transition and better switching noise immunity at the input.

NanoStar package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

8.2 Functional Block Diagram



8.3 Feature Description

This part is available in the TI NanoStar package. It has low static-power consumption with $I_{CC} = 0.9 \mu\text{A}$ maximum and low dynamic power consumption ($C_{pd} = 4.3 \text{ pF}$, Typical at 3.3 V).

The inputs have low capacitance, with typical $C_i = 1.5 \text{ pF}$.

This part has low noise, with overshoot and undershoot less than 10% of V_{CC} .

This part supports partial-power-down mode operation. When this part is powered down ($V_{CC} = 0 \text{ V}$), the leakage current into the device is characterized by I_{off} .

Schmitt-trigger inputs provide hysteresis and consistency in V_{IH} / V_{IL} .

It has a wide operating V_{CC} range of 0.8 V to 3.6 V, and has been optimized for 3.3-V operation.

3.6-V I/O tolerant to support mixed-mode signal operation.

It has a low propagation delay of 5.3 ns at 3.3 V.

It is suitable for point-to-point applications.

8.4 Device Functional Modes

Table 1 lists all the functional modes of the SN74AUP1G57.

Table 1. Function Table

INPUTS			OUTPUT Y
In2	In1	In0	
L	L	L	H
L	L	H	L
L	H	L	H

Table 1. Function Table (continued)

INPUTS			OUTPUT Y
In2	In1	In0	
L	H	H	L
H	L	L	L
H	L	H	L
H	H	L	H
H	H	H	H

8.4.1 Logic Configurations

Table 2 lists all the logic functions of the SN74AUP1G57.

Table 2. Function Selection Table

LOGIC FUNCTION	FIGURE NO.
2-input AND	Figure 4
2-input AND with both inputs inverted	Figure 7
2-input NAND with inverted input	Figure 5, Figure 6
2-input OR with inverted input	Figure 5, Figure 6
2-input NOR	Figure 7
2-input NOR with both inputs inverted	Figure 4
2-input XNOR	Figure 8

<p>Figure 4. 2-Input AND Gate</p>	<p>Figure 5. 2-Input NAND Gate With Inverted A Input</p>
<p>Figure 6. 2-Input NAND Gate With Inverted B Input</p>	<p>Figure 7. 2-Input NOR Gate</p>
<p>Figure 8. 2-Input XNOR Gate</p>	

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74AUP1G57 features configurable multiple functions. The output state is determined by eight patterns of 3-bit input. The user can choose the logic functions AND, NAND, NOR, XNOR, inverter, and noninverter. All inputs can be connected to V_{CC} or GND.

This part can be used in any application where an equivalent single gate would work. The biggest benefit to this part is that it can be used for multiple functions on the same board, reducing the total number of part numbers to be used.

9.2 Typical Application

This application shows how the SN74AUP1G57 can be configured to work as an AND logic gate. This part can be configured to work as an AND logic gate. The capacitor shown is 0.1 μF and should be placed as close as possible to the part.

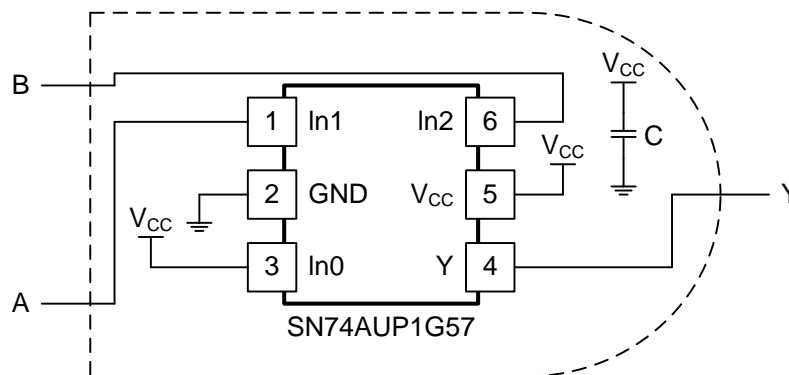


Figure 9. Schematic for AND Gate Configuration of SN74AUP1G57

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits.

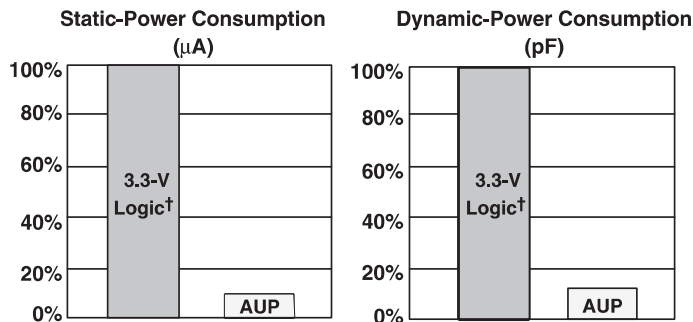
9.2.2 Detailed Design Procedure

1. Recommended Input conditions
 - Rise time and fall time specs. See $(\Delta t/\Delta V)$ in [Recommended Operating Conditions](#)
 - Specified high and low levels. See $(V_{IH}$ and $V_{IL})$ in [Recommended Operating Conditions](#)
 - Inputs are overvoltage tolerant allowing them to go as high as 4.6 V at any valid V_{CC}
2. Recommend output conditions
 - Load currents should not exceed 20 mA on the output and 50 mA total for the part
 - Outputs should not be pulled above $V_{CC} + 0.5$ V.

Typical Application (continued)

9.2.3 Application Curve

The AUP family of single gate logic makes excellent translators for the new lower voltage microprocessors that typically are powered from 0.8 V to 1.2 V. They can drop the voltage of peripheral drivers and accessories that are still powered by 3.3 V to the new microcontroller power levels.



† Single, dual, and triple gates.

Figure 10. AUP – The Lowest-Power Family

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#).

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- μ F bypass capacitor is recommended. If there are multiple pins labeled V_{CC} , then a 0.01- μ F or 0.022- μ F capacitor is recommended for each V_{CC} because the V_{CC} pins will be tied together internally. For devices with dual supply pins operating at different voltages, for example V_{CC} and V_{DD} , a 0.1- μ F bypass capacitor is recommended for each supply pin. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

11 Layout

11.1 Layout Guidelines

Reflections and matching are closely related to the loop antenna theory but are different enough to be discussed separately from the theory. When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self-inductance of the trace which results in the reflection. Not all PCB traces can be straight and therefore some traces must turn corners. [Figure 11](#) shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

11.2 Layout Example

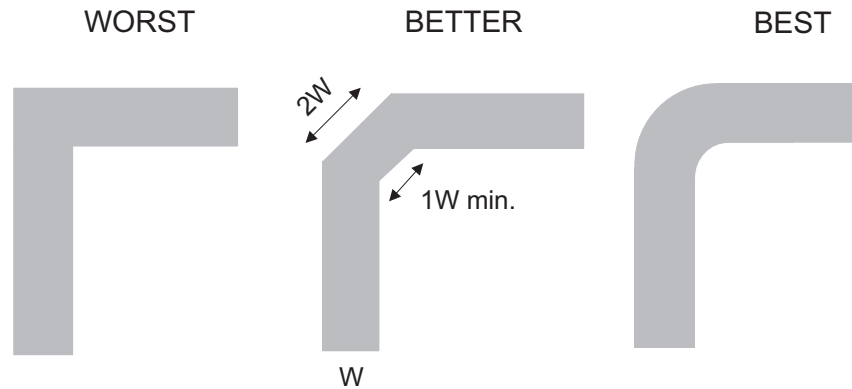


Figure 11. Trace Example

12 Device and Documentation Support

12.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.2 Trademarks

NanoStar, E2E are trademarks of Texas Instruments. All other trademarks are the property of their respective owners.

12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP1G57DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA7R	Samples
SN74AUP1G57DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA7R	Samples
SN74AUP1G57DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HHR	Samples
SN74AUP1G57DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HHR	Samples
SN74AUP1G57DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HHR	Samples
SN74AUP1G57DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HHR	Samples
SN74AUP1G57DRLR	ACTIVE	SOT	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(HH7 ~ HHR)	Samples
SN74AUP1G57DRLRG4	ACTIVE	SOT	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(HH7 ~ HHR)	Samples
SN74AUP1G57DRYR	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HH	Samples
SN74AUP1G57DSFR	ACTIVE	SON	DSF	6	5000	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	HH	Samples
SN74AUP1G57YFPR	ACTIVE	DSBGA	YFP	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM		(HH2 ~ HHN)	Samples
SN74AUP1G57YZPR	ACTIVE	DSBGA	YZP	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(HH7 ~ HHN)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G57DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G57DBVT	SOT-23	DBV	6	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G57DCKR	SC70	DCK	6	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
SN74AUP1G57DCKT	SC70	DCK	6	250	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
SN74AUP1G57DRLR	SOT	DRL	6	4000	180.0	9.5	1.78	1.78	0.69	4.0	8.0	Q3
SN74AUP1G57DRLR	SOT	DRL	6	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
SN74AUP1G57DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP1G57DSFR	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP1G57YFPR	DSBGA	YFP	6	3000	178.0	9.2	0.89	1.29	0.62	4.0	8.0	Q1
SN74AUP1G57YZPR	DSBGA	YZP	6	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

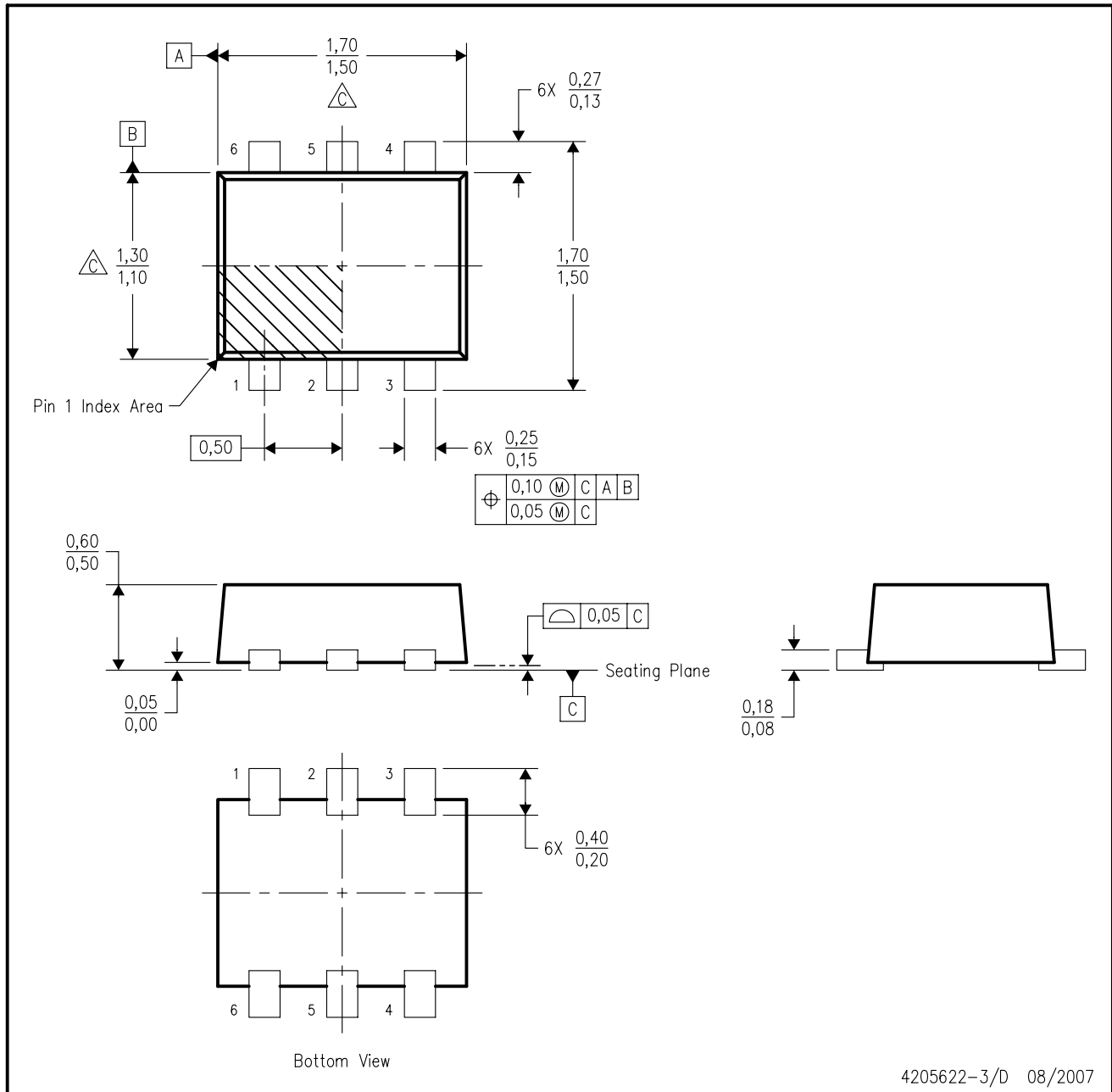
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

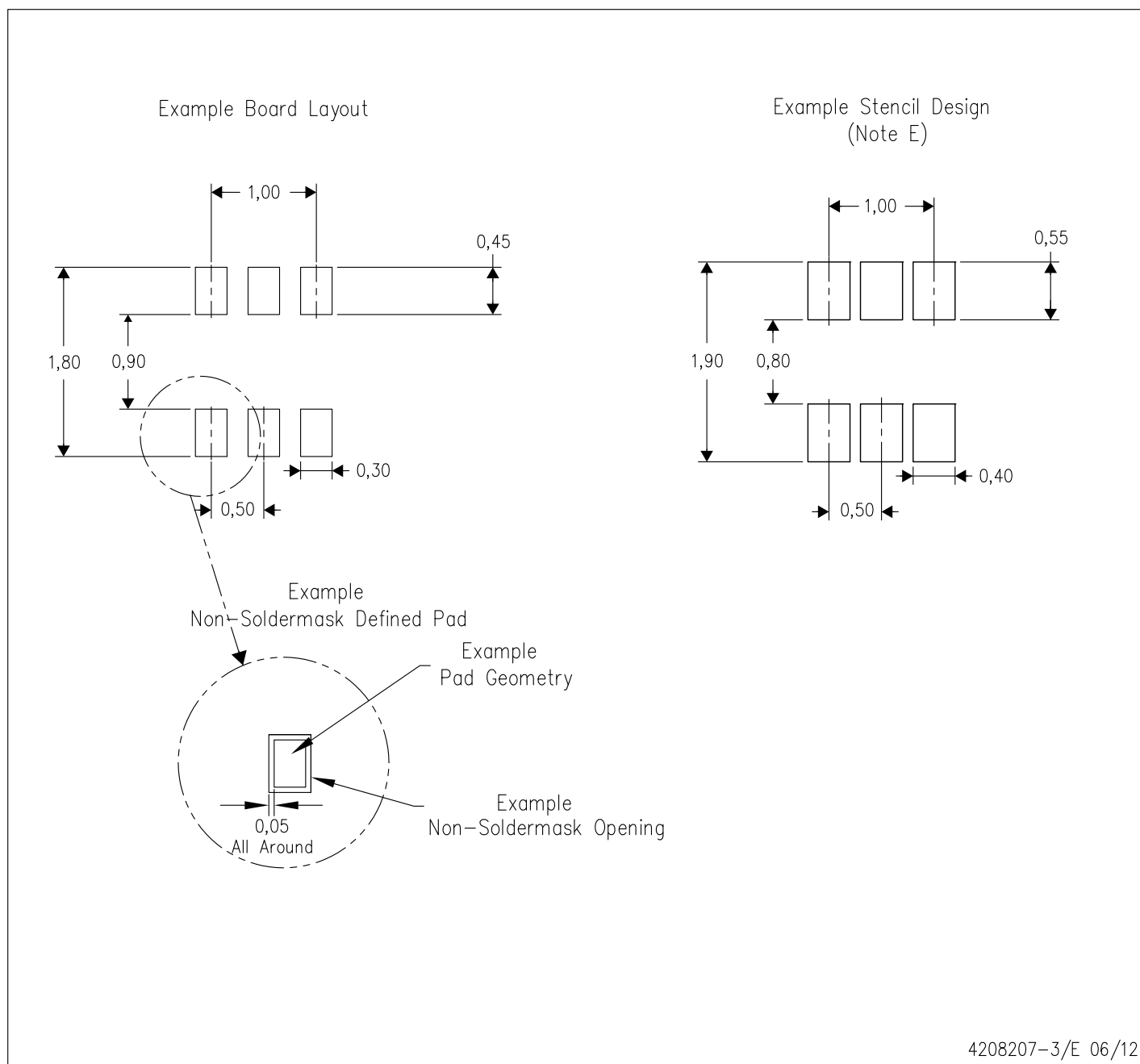
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G57DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
SN74AUP1G57DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0
SN74AUP1G57DCKR	SC70	DCK	6	3000	202.0	201.0	28.0
SN74AUP1G57DCKT	SC70	DCK	6	250	202.0	201.0	28.0
SN74AUP1G57DRLR	SOT	DRL	6	4000	184.0	184.0	19.0
SN74AUP1G57DRLR	SOT	DRL	6	4000	202.0	201.0	28.0
SN74AUP1G57DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP1G57DSFR	SON	DSF	6	5000	184.0	184.0	19.0
SN74AUP1G57YFPR	DSBGA	YFP	6	3000	220.0	220.0	35.0
SN74AUP1G57YZPR	DSBGA	YZP	6	3000	220.0	220.0	35.0

DRL (R-PDSO-N6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
 - D. JEDEC package registration is pending.

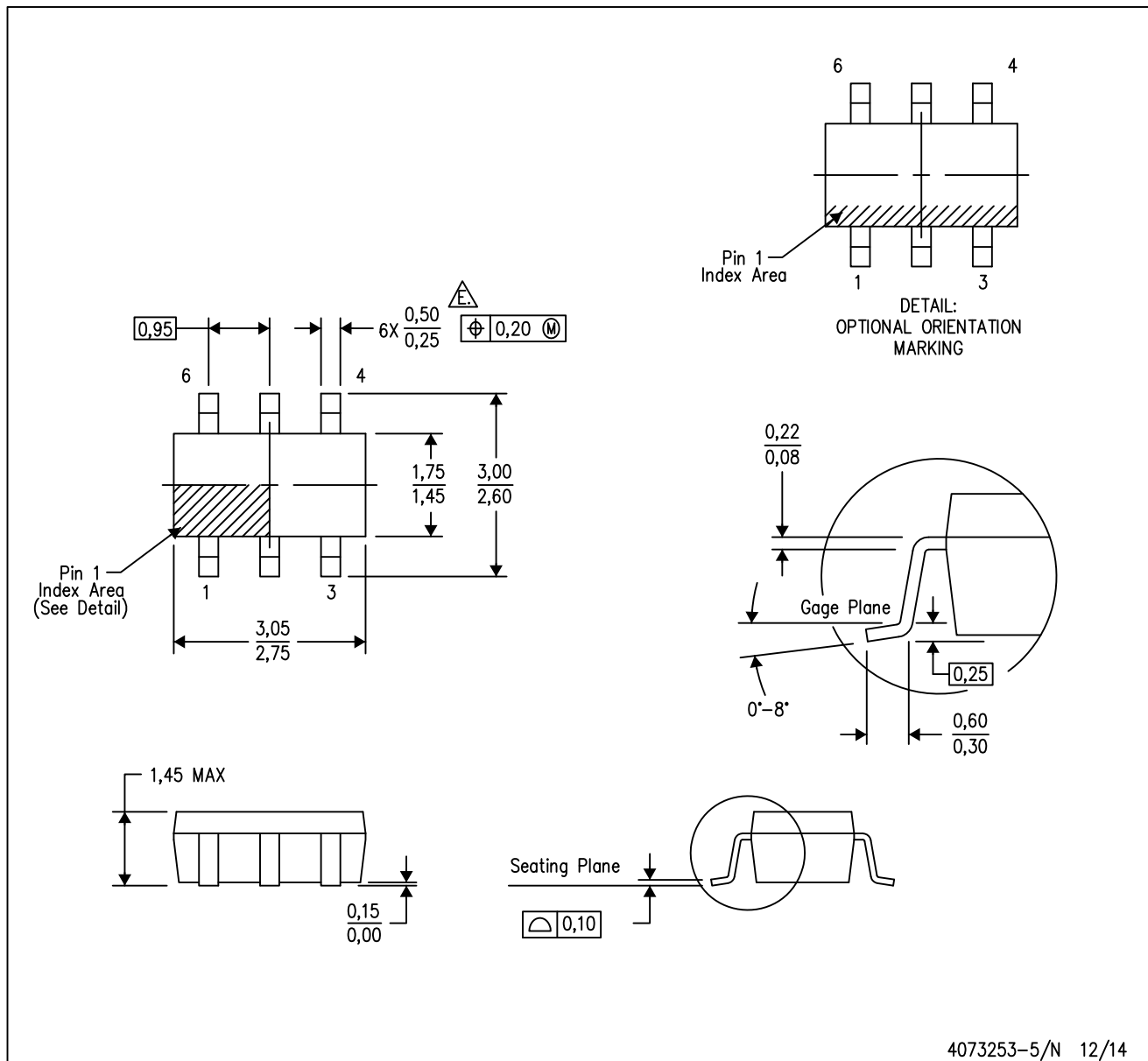


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

MECHANICAL DATA

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- ⚠ Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DCK (R-PDSO-G6)

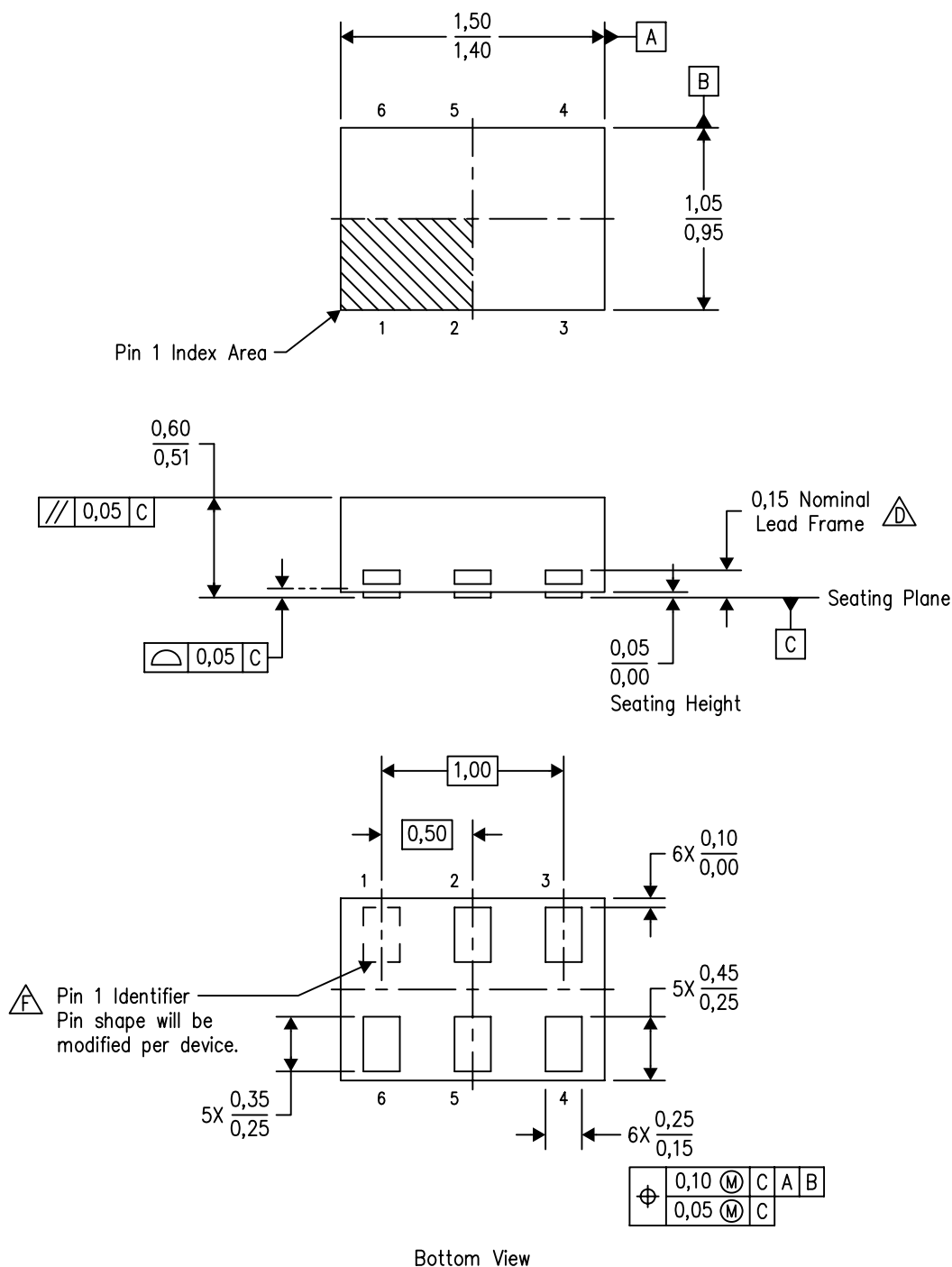
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AB.

DRY (R-PUSON-N6)

PLASTIC SMALL OUTLINE NO-LEAD

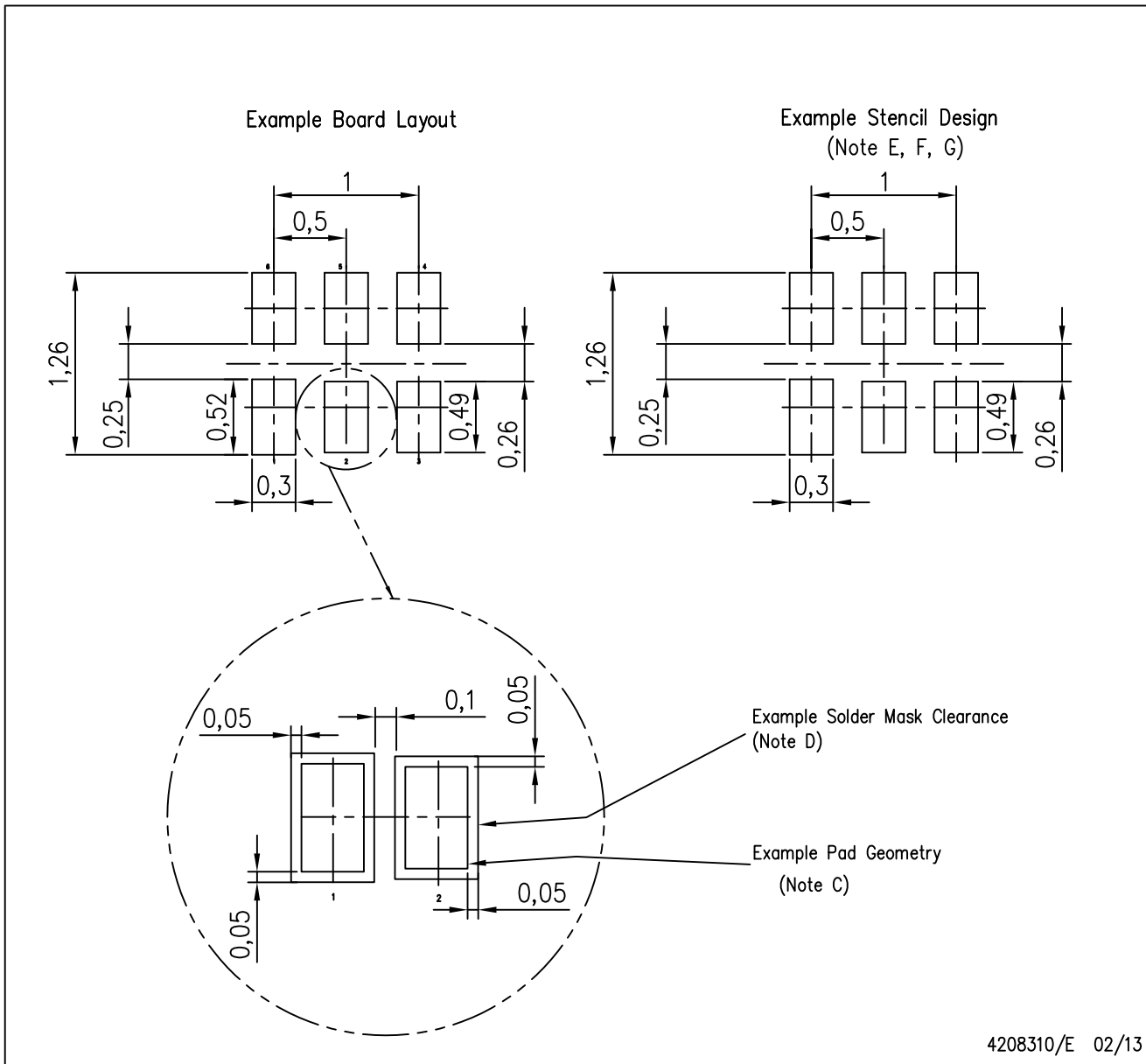


4207181/F 12/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. SON (Small Outline No-Lead) package configuration.
 - $\triangle D$ The exposed lead frame feature on side of package may or may not be present due to alternative lead frame designs.
 - E. This package complies to JEDEC MO-287 variation UFAD.
 - $\triangle F$ See the additional figure in the Product Data Sheet for details regarding the pin 1 identifier shape.

DRY (R-PUSON-N6)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

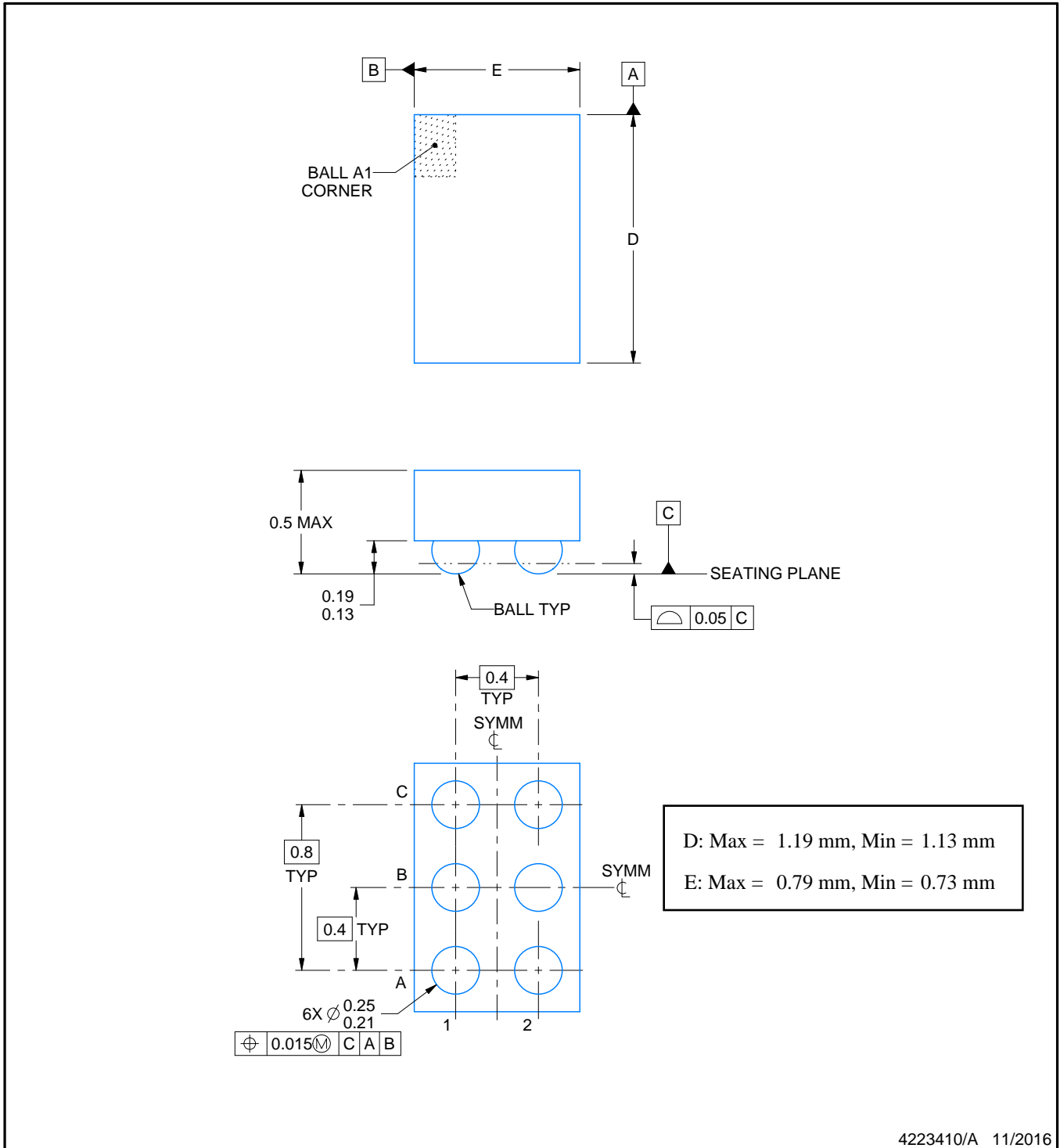
YFP0006



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4223410/A 11/2016

NOTES:

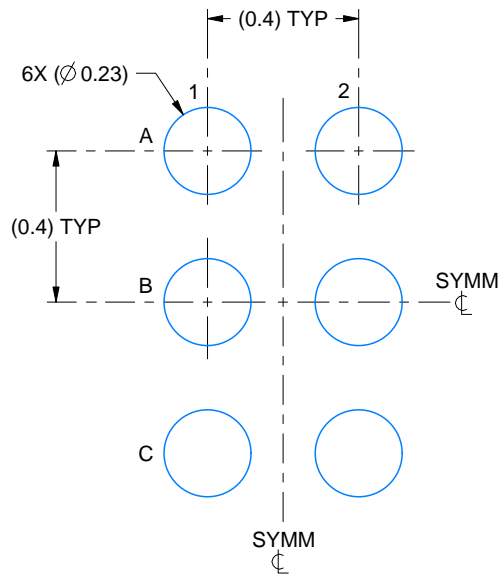
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

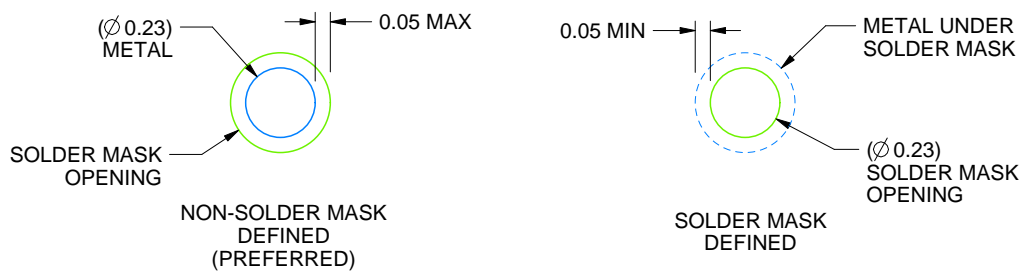
YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:50X



SOLDER MASK DETAILS
NOT TO SCALE

4223410/A 11/2016

NOTES: (continued)

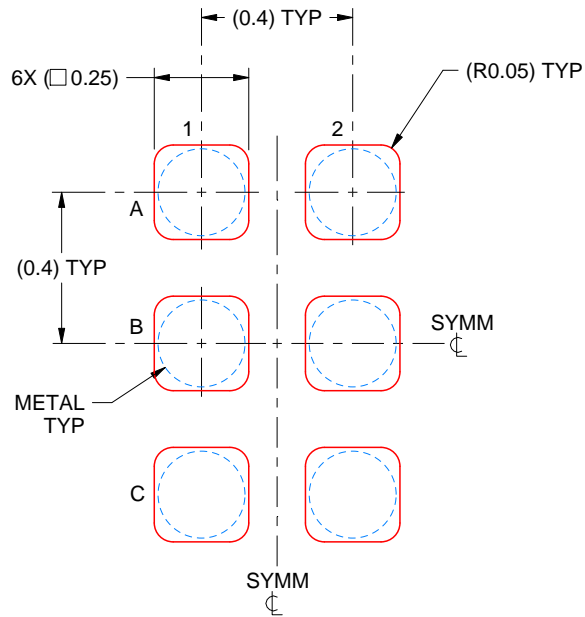
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:50X

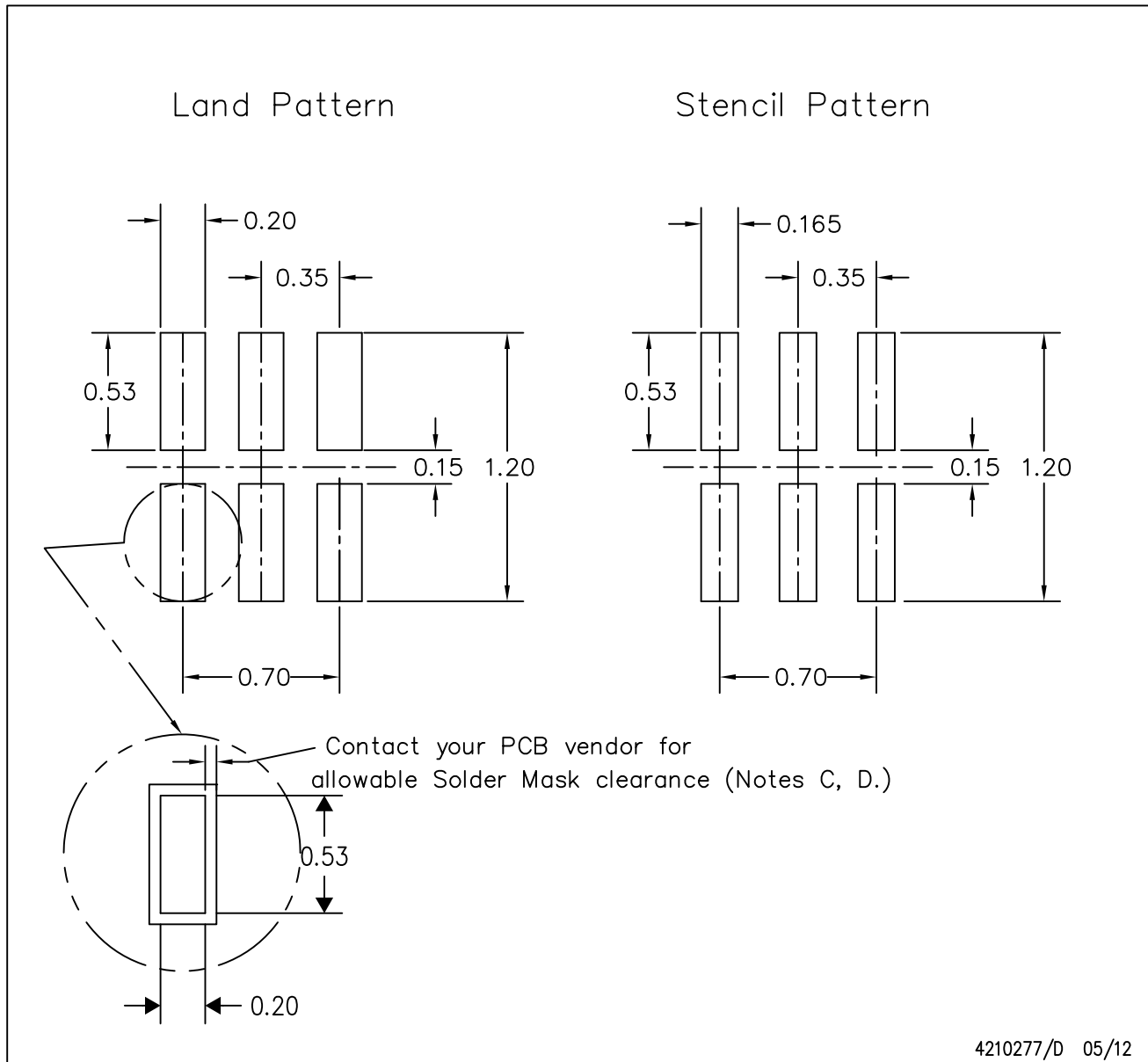
4223410/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

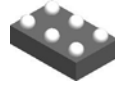
DSF (S-PX2SON-N6)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads. If 2 mil solder mask is outside PCB vendor capability, it is advised to omit solder mask.
 - E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Suggest stencils cut with lasers such as Fiber Laser that produce the greatest positional accuracy.
 - H. Component placement force should be minimized to prevent excessive paste block deformation.

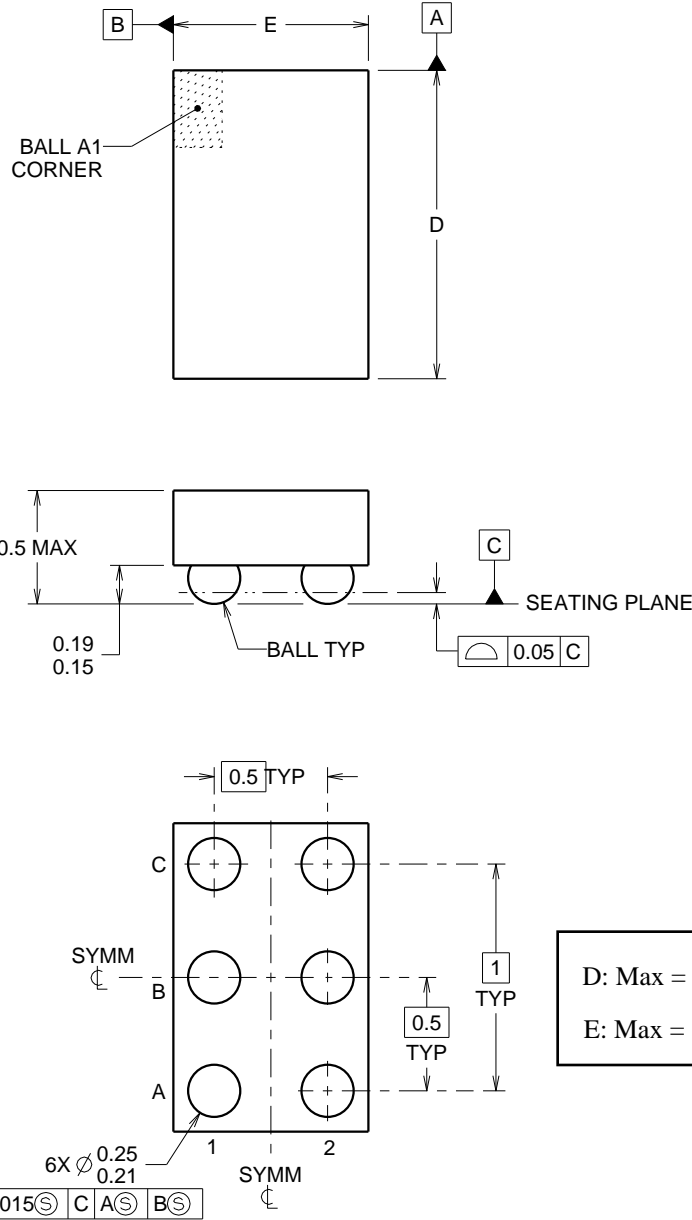
YZP0006



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4219524/A 06/2014

NOTES:

NanoFree Is a trademark of Texas Instruments.

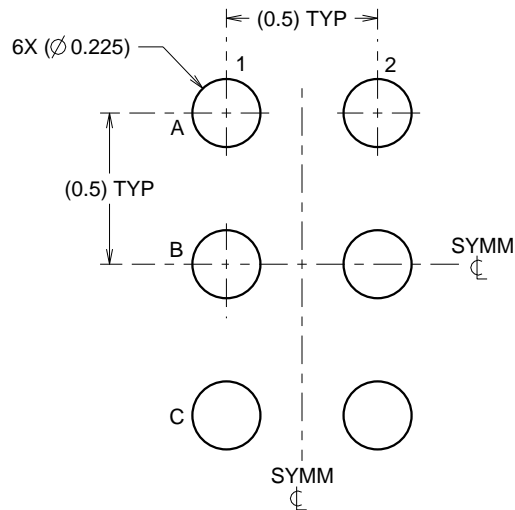
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. NanoFree™ package configuration.

EXAMPLE BOARD LAYOUT

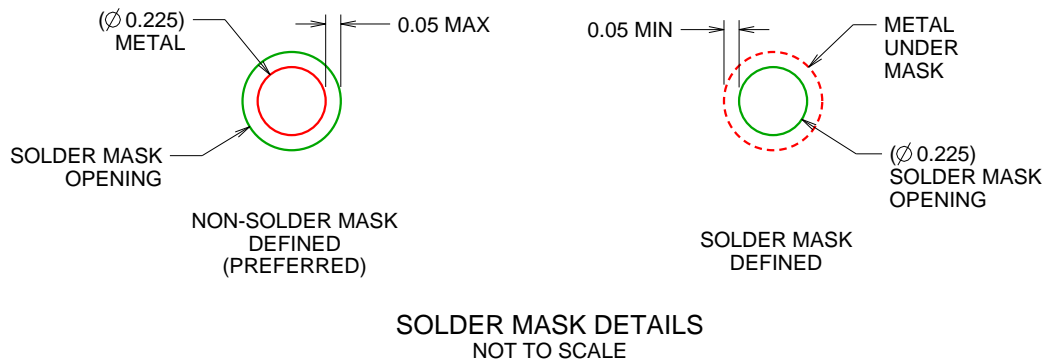
YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:40X



SOLDER MASK DETAILS
NOT TO SCALE

4219524/A 06/2014

NOTES: (continued)

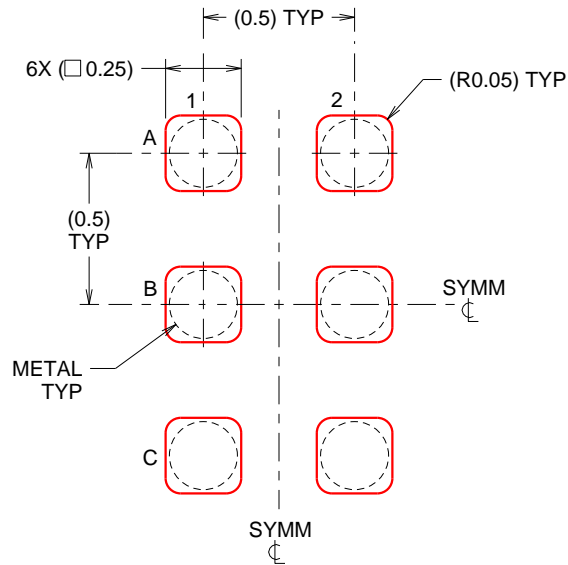
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 (www.ti.com/lit/sbva017).

EXAMPLE STENCIL DESIGN

YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4219524/A 06/2014

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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